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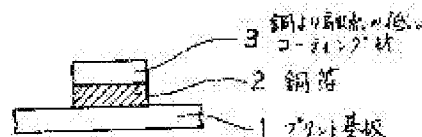
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(54) **PRINTED BOARD PROVIDED WITH FUSE AND MANUFACTURE THEREOF**

(57)Abstract:

PURPOSE: To protect a diode even if a current flows through a circuit provided with a fuse by a method wherein a copper foil section of a fuse pattern section is not coated with solder resist.

CONSTITUTION: A copper foil 2 is provided to a printed board 1, and coating material 3, whose melting point lower than that of copper, is provided thereon instead of coating the foil 2 with solder resist. The copper foil 2 is coated with a material whose fusing point is lower than that of copper, whereby the coating material is melt by heat released from the foil to make it low in a thermal conductivity, so that heat becomes hard to release and a fuse pattern section increases rapidly in temperature and melts to protect a diode.



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